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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	168MHz
Connectivity	CANbus, I²C, SPI, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	48
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 3.6V
Data Converters	A/D 29x12b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mkv44f64vlh16

Kinetis Motor Suite

- Supports velocity and position control of BLDC and PMSM motors
- Implements Field Orient Control (FOC) using Back EMF to improve motor efficiency
- Utilizes SpinTAC control theory that improves overall system performance and reliability

Security and integrity modules

- Hardware CRC module to support fast cyclic redundancy checks
- External Watchdog Monitor (EWM)

NOTE

The 48-pin LQFP package for this product is not yet available. However, it is included in a Package Your Way program for Kinetis MCUs. Visit nxp.com/KPYW for more details.

Orderable part numbers summary[1]

NXP part number	CPU frequency (MHz)	Pin count	Total flash memory (KB)	SRAM (KB)	ADC		eFlexPWM		PWM Nano-Edge	Flex Timers			DAC	FlexCAN	
					ADCA	ADCB	PWMA PWMB	PWMX		FTM0	FTM3	FTM1		CAN0	CAN1
MKV46F256VLL16	168	100	256	32	18ch	20ch	1x8ch	1x4ch	Yes	1x8ch	1x8ch	1x2ch	1	1	1
MKV46F256VLH16	168	64	256	32	13ch	16ch	1x8ch	—	Yes	1x8ch	1x8ch	1x2ch	1	1	1
MKV46F128VLL16	168	100	128	24	18ch	20ch	1x8ch	1x4ch	Yes	1x8ch	1x8ch	1x2ch	1	1	1
MKV46F128VLH16	168	64	128	24	13ch	16ch	1x8ch	—	Yes	1x8ch	1x8ch	1x2ch	1	1	1
MKV44F256VLL16	168	100	256	32	18ch	20ch	1x8ch	1x4ch	Yes	—	—	—	1	1	1
MKV44F256VLH16	168	64	256	32	13ch	16ch	1x8ch	—	Yes	—	—	—	1	1	1
MKV44F128VLL16	168	100	128	24	18ch	20ch	1x8ch	1x4ch	Yes	—	—	—	1	1	1
MKV44F128VLH16	168	64	128	24	13ch	16ch	1x8ch	—	Yes	—	—	—	1	1	1
MKV44F128VLF16[2]	168	48	128	24	11ch	10ch	1x8ch	—	Yes	—	—	—	1	1	—
MKV44F64VLH16	168	64	64	16	13ch	16ch	1x8ch	—	Yes	—	—	—	1	1	1
MKV44F64VLF16[2]	168	48	64	16	11ch	10ch	1x8ch	—	Yes	—	—	—	1	1	—
MKV42F256VLL16	168	100	256	32	18ch	20ch	—	—	—	1x8ch	1x8ch	1x2ch	—	1	1
MKV42F256VLH16	168	64	256	32	13ch	16ch	—	—	—	1x8ch	1x8ch	1x2ch	—	1	1
MKV42F128VLL16	168	100	128	24	18ch	20ch	—	—	—	1x8ch	1x8ch	1x2ch	—	1	1

Table continues on the next page...

2. If the ADC is enabled, minimum V_{DD} is 2.7 V and minimum V_{DDA} is 2.7 V. ADCA and ADCB are not guaranteed to operate below 2.7 V. All other analog modules besides the ADC and Nano-edge will operate down to 1.71 V.
3. If the Nano-edge is enabled, minimum V_{DD} is 3.0 V and minimum V_{DDA} is 3.0 V. Nano-edge is not guaranteed to operate below 3.0 V. All other analog modules besides the ADC and Nano-edge will operate down to 1.71 V.

2.2.2 LVD and POR operating requirements

Table 3. V_{DD} supply LVD and POR operating requirements

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{POR}	Falling V_{DD} POR detect voltage	0.8	1.1	1.5	V	
V_{LVDH}	Falling low-voltage detect threshold — high range (LVDV=01)	2.48	2.56	2.64	V	
	Low-voltage warning thresholds — high range					1
V_{LVW1H}	• Level 1 falling (LVWV=00)	2.62	2.70	2.78	V	
V_{LVW2H}	• Level 2 falling (LVWV=01)	2.72	2.80	2.88	V	
V_{LVW3H}	• Level 3 falling (LVWV=10)	2.82	2.90	2.98	V	
V_{LVW4H}	• Level 4 falling (LVWV=11)	2.92	3.00	3.08	V	
V_{HYSH}	Low-voltage inhibit reset/recover hysteresis — high range	—	±80	—	mV	
V_{LVDL}	Falling low-voltage detect threshold — low range (LVDV=00)	1.54	1.60	1.66	V	
	Low-voltage warning thresholds — low range					1
V_{LVW1L}	• Level 1 falling (LVWV=00)	1.74	1.80	1.86	V	
V_{LVW2L}	• Level 2 falling (LVWV=01)	1.84	1.90	1.96	V	
V_{LVW3L}	• Level 3 falling (LVWV=10)	1.94	2.00	2.06	V	
V_{LVW4L}	• Level 4 falling (LVWV=11)	2.04	2.10	2.16	V	
V_{HYSL}	Low-voltage inhibit reset/recover hysteresis — low range	—	±60	—	mV	
V_{BG}	Bandgap voltage reference	0.97	1.00	1.03	V	
t_{LPO}	Internal low power oscillator period — factory trimmed	900	1000	1100	µs	

1. Rising thresholds are falling threshold + hysteresis voltage

2.2.3 Voltage and current operating behaviors

Table 4. Voltage and current operating behaviors

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{OH}	Output high voltage — normal drive pad					
		V_{DD} – 0.5	—	—	V	
		V_{DD} – 0.5	—	—	V	

Table continues on the next page...

Table 4. Voltage and current operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	• 2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OH} = -10mA • 1.71 V ≤V_{DD} ≤ 2.7 V, I_{OH} = -5mA					
	Output high voltage — High drive pad • 2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OH} = -20mA • 1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OH} = -10mA	 V_{DD} – 0.5 V_{DD} – 0.5	 — —	 — —	 V V	1
I_{OHT}	Output high current total for all ports	—	—	100	mA	
V_{OL}	Output low voltage — open drain pad • 2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OH} = 3 mA • 1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OH} = 1 mA	— —	— —	0.5 0.5	V V	2
V_{OL}	Output low voltage — normal drive pad • 2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OL} = 10 mA • 1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OL} = 5 mA	— —	— —	0.5 0.5	V V	
	Output low voltage — high drive pad • 2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OL} = 20 mA • 1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OL} = 10 mA	— —	— —	0.5 0.5	V V	1
I_{OLT}	Output low current total for all ports	—	—	100	mA	
I_{IN}	Input leakage current, analog and digital pins • V_{SS} ≤ V_{IN} ≤ V_{DD}	—	0.002	0.5	µA	3
R_{PU}	Internal pullup resistors(except RTC_WAKEUP pins)	20	—	50	kΩ	4
R_{PD}	Internal pulldown resistors	20	—	50	kΩ	5

1. High drive pads are PTB0, PTB1, PTC3, PTC4, PTD4, PTD5, PTD6 and PTD7.
2. Open drain pads are PTC6 and PTC7.
3. Measured at VDD=3.6V
4. Measured at V_{DD} supply voltage = V_{DD} min and Vinput = V_{SS}
5. Measured at V_{DD} supply voltage = V_{DD} min and Vinput = V_{DD}

2.2.4 Power mode transition operating behaviors

All specifications except t_{POR} and VLLSx→RUN recovery times in the following table assume this clock configuration:

- CPU and system clocks = 100 MHz
- Bus and flash clock = 25 MHz
- FEI clock mode

Table 5. Power mode transition operating behaviors

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
t_{POR}	After a POR event, amount of time from the point V_{DD} reaches 1.71 V to execution of the first instruction across the operating temperature range of the chip.	—	—	300	µs	
	• VLLS0 → RUN	—	—	173	µs	
	• VLLS1 → RUN	—	—	172	µs	
	• VLLS2 → RUN	—	—	96	µs	
	• VLLS3 → RUN	—	—	96	µs	
	• VLPS → RUN	—	—	5.4	µs	
	• STOP → RUN	—	—	5.4	µs	

2.2.5 Power consumption operating behaviors

NOTE

The maximum values represent characterized results equivalent to the mean plus three times the standard deviation (mean+3σ)

Table 6. Power consumption operating behaviors (All IDDs are Target values)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
I_{DD_RUN}	Run mode current — all peripheral clocks disabled, code executing from flash, excludes IDDA					Core frequency of 25 MHz.
	• @ 1.8V	—	6.8	17.2	mA	
	• @ 3.0V	—	6.9	17.4	mA	
I_{DD_RUN}	Run mode current — all peripheral clocks disabled, code executing from flash, excludes IDDA					Core frequency of 50 MHz.
	• @ 1.8V • @ 3.0V	—	9.9	19.7	mA	

Table continues on the next page...

Table 6. Power consumption operating behaviors (All IDDs are Target values) (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
		—	10.0	19.8	mA	
I_{DD_RUN}	Run mode current — all peripheral clocks disabled, code executing from flash, excludes IDDA					Core frequency of 100 MHz.
	• @ 1.8V	—	17.0	25.9	mA	
	• @ 3.0V	—	17.2	26.1	mA	
I_{DD_HSRUN}	Run mode current — all peripheral clocks disabled, code executing from flash, excludes IDDA					Core frequency of 168 MHz.
	• @ 1.8V	—	26.3	45.3	mA	
	• @ 3.0V	—	26.5	45.5	mA	
I_{DD_HSRUN}	Run mode current — all peripheral clocks enabled, code executing from flash,excludes IDDA					Core frequency of 168 MHz. Nanoedge module at 84 MHz.
	• @ 3.0V					
	• @ 25°C	—	34.0	45.5	mA	
	• @ 105°C	—	39.0	53.2	mA	
I_{DD_WAIT}	Wait mode high frequency current at 3.0 V — all peripheral clocks disabled	—	8.9	—	mA	
I_{DD_VLPR}	Very-low-power run mode current at 3.0 V — all peripheral clocks disabled	—	0.58	—	mA	Core frequency of 4 Mhz.
I_{DD_VLPR}	Very-low-power run mode current at 3.0 V — all peripheral clocks enabled	—	0.83	—	mA	Core frequency of 4 Mhz.
I_{DD_VLPW}	Very-low-power wait mode current at 3.0 V — all peripheral clocks disabled	—	0.34	—	mA	Bus frequency of 2 MHz.
I_{DD_STOP}	Stop mode current at 3.0 V					
	• @ –40 to 25°C	—	0.43	2.03	mA	
	• @ 70°C	—	1.16	4.27	mA	
	• @ 105°C	—	3.05	10.13	mA	
I_{DD_VLPS}	Very-low-power stop mode current at 3.0 V					
	• @ –40 to 25°C	—	58	218	µA	
	• @ 70°C	—	280	1340	µA	
	• @ 105°C	—	924	2870	µA	
I_{DD_VLLS3}	Very low-leakage stop mode 3 current at 3.0 V					
	• @ –40 to 25°C	—	2.8	5.3	µA	
	• @ 70°C	—	9.6	35.1	µA	
	• @ 105°C	—	37.4	134.8	µA	
I_{DD_VLLS2}	Very low-leakage stop mode 2 current at 3.0 V					

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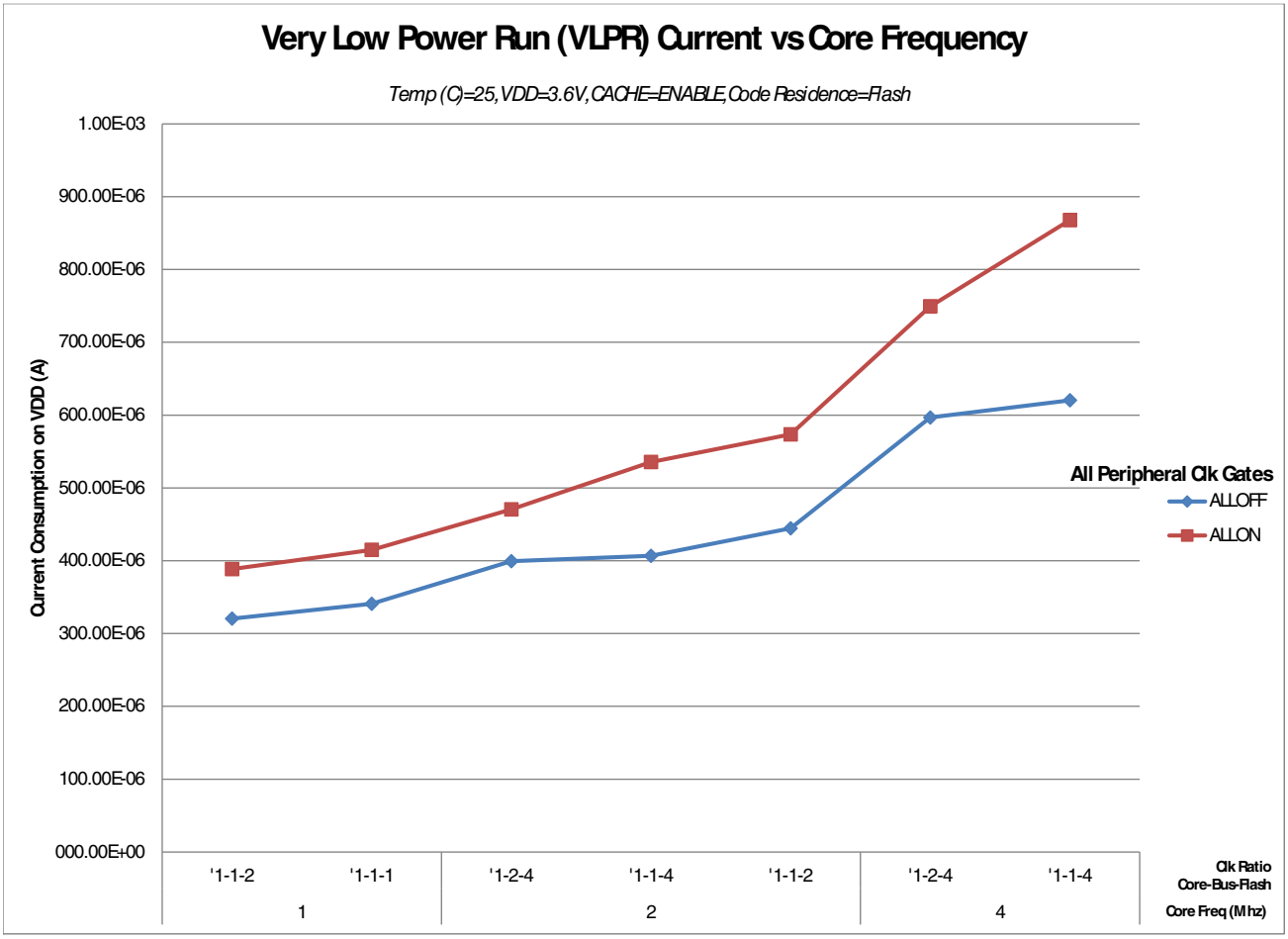


Figure 4. VLPR mode current vs. core frequency

2.2.6 EMC radiated emissions operating behaviors

NOTE

EMC measurements to IC-level IEC standards are available from NXP on request.

Table 8. EMC radiated emissions operating behaviors

Symbol	Description	Frequency band (MHz)	Typ.	Unit	Notes
V_{RE1}	Radiated emissions voltage, band 1	0.15–50	20	dBµV	1, 2
V_{RE2}	Radiated emissions voltage, band 2	50–150	18	dBµV	
V_{RE3}	Radiated emissions voltage, band 3	150–500	14	dBµV	
V_{RE4}	Radiated emissions voltage, band 4	500–1000	8	dBµV	
V_{RE_IEC}	IEC level	0.15–1000	L	—	2, 3

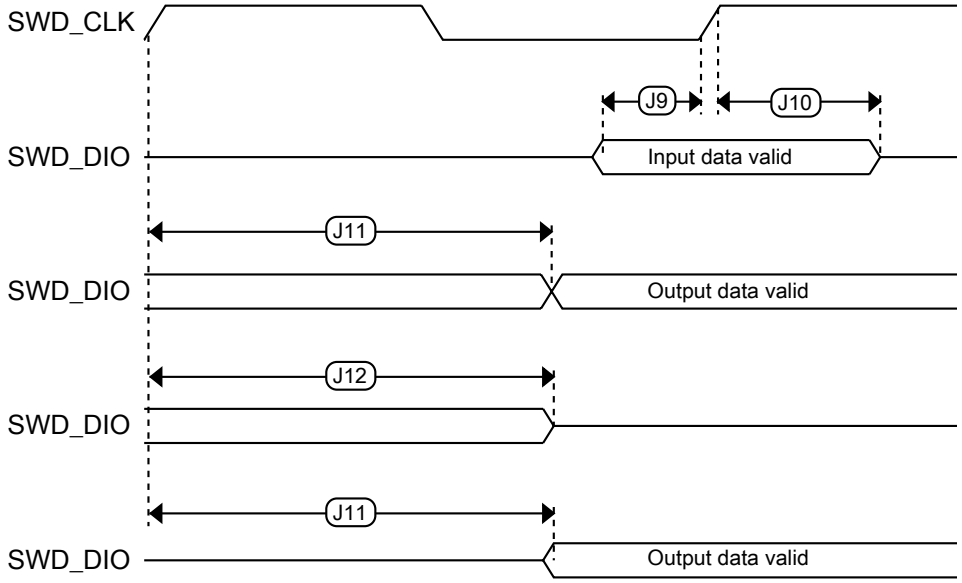


Figure 6. Serial wire data timing

3.1.2 Debug trace timing specifications

Table 15. Debug trace operating behaviors

Symbol	Description	Min.	Max.	Unit
T_{cyc}	Clock period	Frequency dependent		MHz
T_{wl}	Low pulse width	2	—	ns
T_{wh}	High pulse width	2	—	ns
T_r	Clock and data rise time	—	3	ns
T_f	Clock and data fall time	—	3	ns
T_s	Data setup	3	1.5	ns
T_h	Data hold	2	1.0	ns

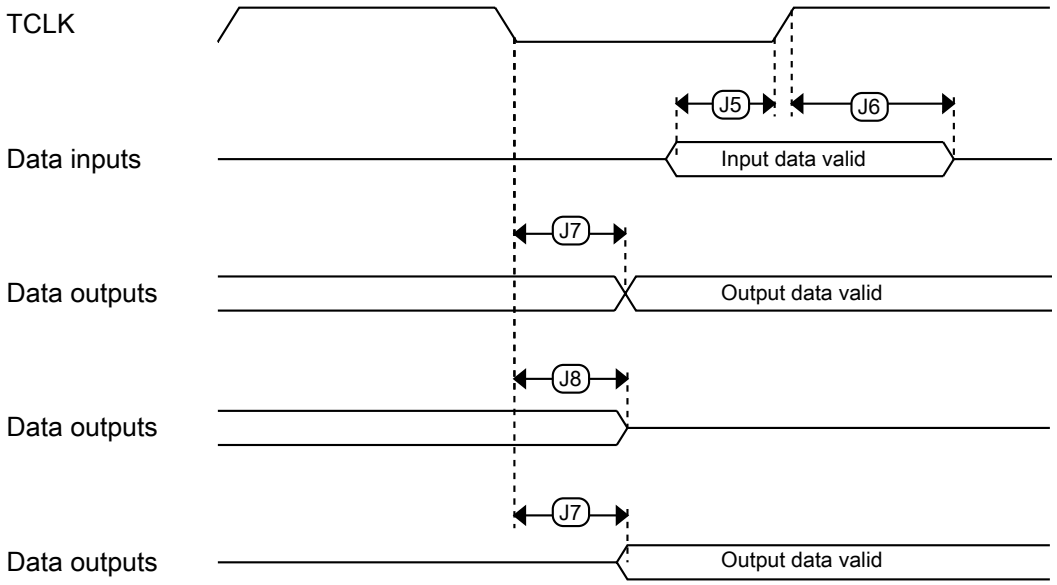


Figure 10. Boundary scan (JTAG) timing

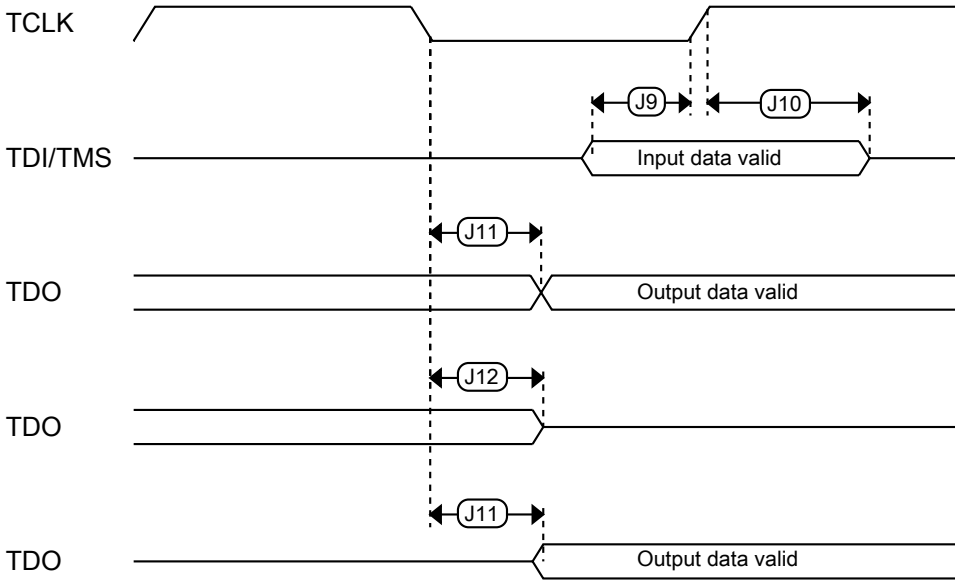


Figure 11. Test Access Port timing

Table 18. MCG specifications (continued)

Symbol	Description		Min.	Typ.	Max.	Unit	Notes
f_{loc_high}	Loss of external clock minimum frequency — RANGE = 01, 10, or 11		(16/5) x f_{ints_t}	—	—	kHz	
FLL							
f_{fll_ref}	FLL reference frequency range		31.25	—	39.0625	kHz	
f_{dco}	DCO output frequency range	Low range (DRS=00) 640 × f_{fll_ref}	20	20.97	25	MHz	2, 3
		Mid range (DRS=01) 1280 × f_{fll_ref}	40	41.94	50	MHz	
		Mid-high range (DRS=10) 1920 × f_{fll_ref}	60	62.91	75	MHz	
		High range (DRS=11) 2560 × f_{fll_ref}	80	83.89	100	MHz	
$f_{dco\_t\_DMX32}$	DCO output frequency	Low range (DRS=00) 732 × f_{fll_ref}	—	23.99	—	MHz	4, 5
		Mid range (DRS=01) 1464 × f_{fll_ref}	—	47.97	—	MHz	
		Mid-high range (DRS=10) 2197 × f_{fll_ref}	—	71.99	—	MHz	
		High range (DRS=11) 2929 × f_{fll_ref}	—	95.98	—	MHz	
J_{cyc_fll}	FLL period jitter • f_{DCO} = 48 MHz • f_{DCO} = 98 MHz		— —	180 150	— —	ps	
$t_{fll\_acquire}$	FLL target frequency acquisition time		—	—	1	ms	6
PLL							
f_{pll_ref}	PLL reference frequency range		8	—	16	MHz	
f_{vcoclk_2x}	VCO output frequency		220	—	480	MHz	
f_{vcoclk}	PLL output frequency		110	—	240	MHz	
f_{vcoclk_90}	PLL quadrature output frequency		110	—	240	MHz	
I_{pll}	PLL operating current • VCO @ 176 MHz ($f_{osc\_hi\_1}$ = 32 MHz, f_{pll_ref} = 8 MHz, VDIV multiplier = 22)		—	2.8	—	mA	7
I_{pll}	PLL operating current • VCO @ 360 MHz ($f_{osc\_hi\_1}$ = 32 MHz, f_{pll_ref} = 8 MHz, VDIV multiplier = 45)		—	4.7	—	mA	7
J_{cyc_pll}	PLL period jitter (RMS) • f_{vco} = 48 MHz • f_{vco} = 120 MHz		— —	120 75	— —	ps ps	8
J_{acc_pll}	PLL accumulated jitter over 1µs (RMS)						8

Table continues on the next page...

Table 19. Oscillator DC electrical specifications (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	• 8 MHz	—	500	—	µA	
	• 16 MHz	—	2.5	—	mA	
	• 24 MHz	—	3	—	mA	
	• 32 MHz	—	4	—	mA	
C_x	EXTAL load capacitance	—	—	—		2, 3
C_y	XTAL load capacitance	—	—	—		2, 3
R_F	Feedback resistor — low-frequency, low-power mode (HGO=0)	—	—	—	MΩ	2, 4
	Feedback resistor — low-frequency, high-gain mode (HGO=1)	—	10	—	MΩ	
	Feedback resistor — high-frequency, low-power mode (HGO=0)	—	—	—	MΩ	
	Feedback resistor — high-frequency, high-gain mode (HGO=1)	—	1	—	MΩ	
R_S	Series resistor — low-frequency, low-power mode (HGO=0)	—	—	—	kΩ	
	Series resistor — low-frequency, high-gain mode (HGO=1)	—	200	—	kΩ	
	Series resistor — high-frequency, low-power mode (HGO=0)	—	—	—	kΩ	
	Series resistor — high-frequency, high-gain mode (HGO=1)	—	0	—	kΩ	
V_{pp}[5]	Peak-to-peak amplitude of oscillation (oscillator mode) — low-frequency, low-power mode (HGO=0)	—	0.6	—	V	
	Peak-to-peak amplitude of oscillation (oscillator mode) — low-frequency, high-gain mode (HGO=1)	—	V_{DD}	—	V	
	Peak-to-peak amplitude of oscillation (oscillator mode) — high-frequency, low-power mode (HGO=0)	—	0.6	—	V	
	Peak-to-peak amplitude of oscillation (oscillator mode) — high-frequency, high-gain mode (HGO=1)	—	V_{DD}	—	V	

1. V_{DD}=3.3 V, Temperature =25 °C
2. See crystal or resonator manufacturer's recommendation
3. C_x,C_y can be provided by using the integrated capacitors when the low frequency oscillator (RANGE = 00) is used. For all other cases external capacitors must be used.
4. When low power mode is selected, R_F is integrated and must not be attached externally.
5. The EXTAL and XTAL pins should only be connected to required oscillator components and must not be connected to any other devices.

Table 25. 12-bit ADC electrical specifications (continued)

Characteristic	Symbol	Min	Typ	Max	Unit
Monotonicity					
Offset[6] • 1x gain mode • 2x gain mode • 4x gain mode	V_{OFFSET}			 +/- 25 +/- 20 +50, -10	LSB[4]
Gain Error	E_{GAIN}		0.0002	—	%
AC Specifications[7]					
Signal to Noise Ratio	SNR		59		dB
Total Harmonic Distortion	THD		64		dB
Spurious Free Dynamic Range	SFDR		65		dB
Signal to Noise plus Distortion	SINAD		59		dB
Effective Number of Bits	ENOB		9.1		bits
ADC Inputs					
Input Leakage Current	I_{IN}		0	+/-2	µA
Input Injection Current [8]	I_{INJ}			+/-3	mA
Input Capacitance Sampling Capacitor	C_{ADI}		4.8		pF

1. If the ADC's reference is from V_{DDA}: When V_{DDA} is below 2.7 V, then the ADC functions, but the ADC specifications are not guaranteed.
2. When the input is at the V_{refl} level, then the resulting output will be all zeros (hex 000), plus any error contribution due to offset and gain error. When the input is at the V_{refh} level, then the output will be all ones (hex FFF), minus any error contribution due to offset and gain error.
3. ADC clock duty cycle min/max is 45/55% .
4. D_{NL} and I_{NL} conversion accuracy is not guaranteed from V_{REFL} to V_{REFL} + 0025 and V_{REFH} to V_{REFH}-0025.
5. LSB = Least Significant Bit = 0.806 mV at 3.3 V VDDA, x1 Gain Setting
6. Offset over the conversion range of 0025 to 4070, with internal/external reference.
7. Measured when converting a 1 kHz input Full Scale sine wave.
8. The current that can be *injected into* or *sourced from* an unselected ADC input, without affecting the performance of the ADC.

3.6.1.1 Equivalent circuit for ADC inputs

The following figure shows the ADC input circuit during sample and hold. S1 and S2 are always opened/closed at non-overlapping phases, and both S1 and S2 operate at the ADC clock frequency. The following equation gives equivalent input impedance when the input is selected.

$$\frac{1}{(\text{ADC ClockRate}) \times 1.4 \times 10^{-12}} + 100\,ohm + 125\,ohm$$

Table 38. Master mode DSPI timing fast pads (full voltage range)

Num	Description	Min.	Max.	Unit	Notes
	Operating voltage	1.71	3.6	V	1
	Frequency of operation	—	25	MHz	
DS1	DSPI_SCK output cycle time	4 x t_{BUS}	—	ns	
DS2	DSPI_SCK output high/low time	(t_{SCK}/2) - 4	($t_{SCK/2)}$ + 4	ns	
DS3	DSPI_PCS*n* valid to DSPI_SCK delay	(t_{BUS} x 2) – 4	—	ns	2
DS4	DSPI_SCK to DSPI_PCS*n* invalid delay	(t_{BUS} x 2) – 4	—	ns	3
DS5	DSPI_SCK to DSPI_SOUT valid	—	10	ns	
DS6	DSPI_SCK to DSPI_SOUT invalid	-7.8	—	ns	
DS7	DSPI_SIN to DSPI_SCK input setup	17	—	ns	
DS8	DSPI_SCK to DSPI_SIN input hold	0	—	ns	

1. The DSPI module can operate across the entire operating voltage for the processor, but to run across the full voltage range the maximum frequency of operation is reduced.
2. The delay is programmable in SPIx_CTARn[PSSCK] and SPIx_CTARn[CSSCK].
3. The delay is programmable in SPIx_CTARn[PASC] and SPIx_CTARn[ASC].

Table 39. Master mode DSPI timing open drain pads (full voltage range)

Num	Description	Min.	Max.	Unit	Notes
	Operating voltage	1.71	3.6	V	1
	Frequency of operation	—	18.75	MHz	
DS1	DSPI_SCK output cycle time	4 x t_{BUS}	—	ns	
DS2	DSPI_SCK output high/low time	(t_{SCK}/2) - 4	($t_{SCK/2)}$ + 4	ns	
DS3	DSPI_PCS*n* valid to DSPI_SCK delay	(t_{BUS} x 2) – 4	—	ns	2
DS4	DSPI_SCK to DSPI_PCS*n* invalid delay	(t_{BUS} x 2) – 4	—	ns	3
DS5	DSPI_SCK to DSPI_SOUT valid	—	26	ns	
DS6	DSPI_SCK to DSPI_SOUT invalid	-7.8	—	ns	
DS7	DSPI_SIN to DSPI_SCK input setup	24	—	ns	
DS8	DSPI_SCK to DSPI_SIN input hold	0	—	ns	

1. The DSPI module can operate across the entire operating voltage for the processor, but to run across the full voltage range the maximum frequency of operation is reduced.
2. The delay is programmable in SPIx_CTARn[PSSCK] and SPIx_CTARn[CSSCK].
3. The delay is programmable in SPIx_CTARn[PASC] and SPIx_CTARn[ASC].

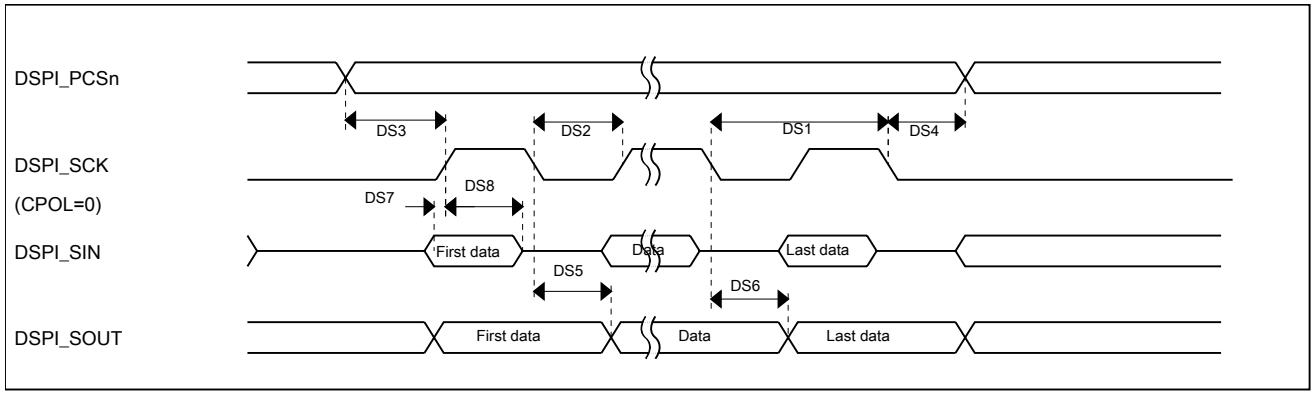


Figure 20. DSPI classic SPI timing — master mode

Table 40. Slave mode DSPI timing for normal pads (full voltage range)

Num	Description	Min.	Max.	Unit
	Operating voltage	1.71	3.6	V
	Frequency of operation	—	12.5	MHz
DS9	DSPI_SCK input cycle time	8 x t_{BUS}	—	ns
DS10	DSPI_SCK input high/low time	(t_{SCK}/2) - 4	($t_{SCK/2)}$ + 4	ns
DS11	DSPI_SCK to DSPI_SOUT valid	—	27.5	ns
DS12	DSPI_SCK to DSPI_SOUT invalid	0	—	ns
DS13	DSPI_SIN to DSPI_SCK input setup	2.5	—	ns
DS14	DSPI_SCK to DSPI_SIN input hold	7	—	ns
DS15	$\overline{\text{DSPI\_SS}}$ active to DSPI_SOUT driven	—	22	ns
DS16	$\overline{\text{DSPI\_SS}}$ inactive to DSPI_SOUT not driven	—	22	ns

Table 41. Slave mode DSPI timing for fast pads (full voltage range)

Num	Description	Min.	Max.	Unit
	Operating voltage	1.71	3.6	V
	Frequency of operation	—	18.75	MHz
DS9	DSPI_SCK input cycle time	8 x t_{BUS}	—	ns
DS10	DSPI_SCK input high/low time	(t_{SCK}/2) - 4	($t_{SCK/2)}$ + 4	ns
DS11	DSPI_SCK to DSPI_SOUT valid	—	20.5	ns
DS12	DSPI_SCK to DSPI_SOUT invalid	0	—	ns
DS13	DSPI_SIN to DSPI_SCK input setup	2.5	—	ns
DS14	DSPI_SCK to DSPI_SIN input hold	7	—	ns
DS15	$\overline{\text{DSPI\_SS}}$ active to DSPI_SOUT driven	—	15	ns
DS16	$\overline{\text{DSPI\_SS}}$ inactive to DSPI_SOUT not driven	—	15	ns

Table 42. Slave mode DSPI timing for open drain pads (full voltage range)

Num	Description	Min.	Max.	Unit
	Operating voltage	1.71	3.6	V
	Frequency of operation	—	9.375	MHz
DS9	DSPI_SCK input cycle time	8 x t_{BUS}	—	ns
DS10	DSPI_SCK input high/low time	(t_{SCK}/2) - 4	($t_{SCK/2}$) + 4	ns
DS11	DSPI_SCK to DSPI_SOUT valid	—	43.5	ns
DS12	DSPI_SCK to DSPI_SOUT invalid	0	—	ns
DS13	DSPI_SIN to DSPI_SCK input setup	2.5	—	ns
DS14	DSPI_SCK to DSPI_SIN input hold	7	—	ns
DS15	$\overline{\text{DSPI\_SS}}$ active to DSPI_SOUT driven	—	38	ns
DS16	$\overline{\text{DSPI\_SS}}$ inactive to DSPI_SOUT not driven	—	38	ns

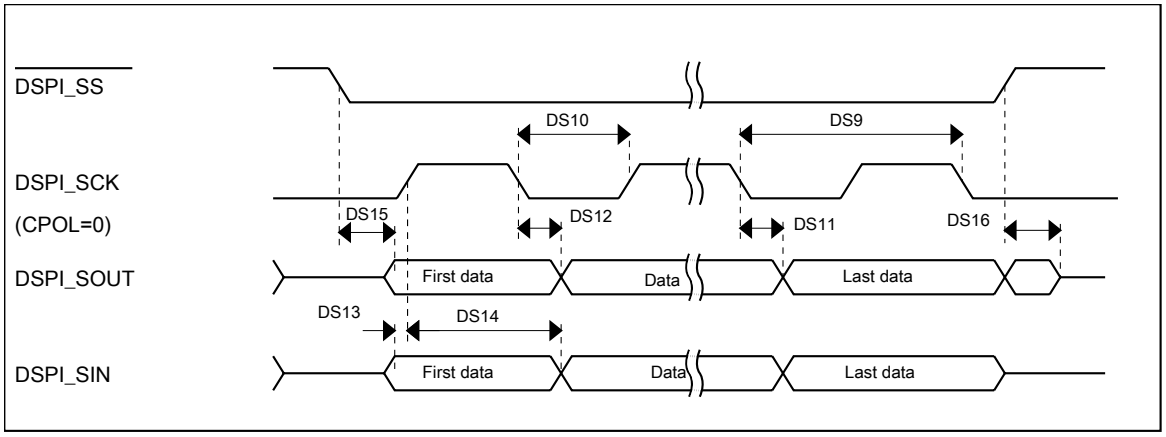


Figure 21. DSPI classic SPI timing — slave mode

3.9.3 I²C

See General switching specifications.

3.9.4 UART

See General switching specifications.

3.10 Kinetis Motor Suite (KMS)

100 LQFP	64 LQFP	48 LQFP	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7
1	1	—	PTE0/ CLKOUT32K	ADCB_CH6f	ADCB_CH6f	PTE0/ CLKOUT32K		UART1_TX	XBAR0_ OUT10	XBAR0_IN11		
2	2	—	PTE1/ LLWU_P0	ADCB_CH7f	ADCB_CH7f	PTE1/ LLWU_P0		UART1_RX	XBAR0_ OUT11	XBAR0_IN7		
3	—	—	PTE2/ LLWU_P1	ADCB_CH6g	ADCB_CH6g	PTE2/ LLWU_P1		UART1_ CTS_b				
4	—	—	PTE3	ADCB_CH7g	ADCB_CH7g	PTE3		UART1_ RTS_b				
5	—	—	PTE4/ LLWU_P2	DISABLED		PTE4/ LLWU_P2						
6	—	—	PTE5	DISABLED		PTE5					FTM3_CH0	
7	—	—	PTE6/ LLWU_P16	DISABLED		PTE6/ LLWU_P16					FTM3_CH1	
8	3	1	VDD	VDD	VDD							
9	4	2	VSS	VSS	VSS							
10	5	3	PTE16	ADCA_CH0	ADCA_CH0	PTE16	SPI0_PCS0	UART1_TX	FTM_CLKIN0		FTM0_FLT3	
11	6	4	PTE17/ LLWU_P19	ADCA_CH1	ADCA_CH1	PTE17/ LLWU_P19	SPI0_SCK	UART1_RX	FTM_CLKIN1		LPTMR0_ ALT3	
12	7	5	PTE18/ LLWU_P20	ADCB_CH0	ADCB_CH0	PTE18/ LLWU_P20	SPI0_SOUT	UART1_ CTS_b	I2C0_SDA			
13	8	6	PTE19	ADCB_CH1	ADCB_CH1	PTE19	SPI0_SIN	UART1_ RTS_b	I2C0_SCL		CMP3_OUT	
14	—	—	ADCA_CH6a	ADCA_CH6a	ADCA_CH6a							
15	—	—	ADCA_CH7a	ADCA_CH7a	ADCA_CH7a							
16	—	7	PTE20	ADCA_CH6b	ADCA_CH6b	PTE20		FTM1_CH0	UART0_TX			
17	—	8	PTE21	ADCA_CH7b	ADCA_CH7b	PTE21		FTM1_CH1	UART0_RX			
18	9	—	ADCA_CH2	ADCA_CH2	ADCA_CH2							
19	10	—	ADCA_CH3	ADCA_CH3	ADCA_CH3							
20	11	—	ADCA_CH6c	ADCA_CH6c	ADCA_CH6c							
21	12	—	ADCA_CH7c	ADCA_CH7c	ADCA_CH7c							
22	13	9	VDDA	VDDA	VDDA							
23	14	10	VREFH	VREFH	VREFH							
24	15	11	VREFL	VREFL	VREFL							
25	16	12	VSSA	VSSA	VSSA							
26	17	13	PTE29	ADCA_CH4/ CMP1_IN5/ CMP0_IN5	ADCA_CH4/ CMP1_IN5/ CMP0_IN5	PTE29		FTM0_CH2		FTM_CLKIN0		
27	18	14	PTE30	DAC0_OUT/ CMP1_IN3/ ADCA_CH5	DAC0_OUT/ CMP1_IN3/ ADCA_CH5	PTE30		FTM0_CH3		FTM_CLKIN1		
28	19	—	ADCA_CH6d/ CMP0_IN4/ CMP2_IN3	ADCA_CH6d/ CMP0_IN4/ CMP2_IN3	ADCA_CH6d/ CMP0_IN4/ CMP2_IN3							
29	—	—	VSS	VSS	VSS							

100 LQFP	64 LQFP	48 LQFP	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7
82	55	—	PTC10	ADCB_CH7d	ADCB_CH7d	PTC10		FTM3_CH6				
83	56	—	PTC11/ LLWU_P11	ADCB_CH6e	ADCB_CH6e	PTC11/ LLWU_P11		FTM3_CH7				
84	—	—	PTC12	DISABLED		PTC12			FTM_CLKIN0		FTM3_FLT0	
85	—	—	PTC13	DISABLED		PTC13			FTM_CLKIN1			
86	—	—	PTC14	DISABLED		PTC14		I2C0_SCL				
87	—	—	PTC15	DISABLED		PTC15		I2C0_SDA				
88	—	—	VSS	VSS	VSS							
89	—	—	VDD	VDD	VDD							
90	—	—	PTC16	DISABLED		PTC16	CAN1_RX					
91	—	—	PTC17	DISABLED		PTC17	CAN1_TX					
92	—	—	PTC18	DISABLED		PTC18						
93	57	41	PTD0/ LLWU_P12	DISABLED		PTD0/ LLWU_P12	SPI0_PCS0		FTM3_CH0	FTM0_CH0	FLEXPWMA_ A0	
94	58	42	PTD1	ADCA_CH7f	ADCA_CH7f	PTD1	SPI0_SCK		FTM3_CH1	FTM0_CH1	FLEXPWMA_ B0	
95	59	43	PTD2/ LLWU_P13	DISABLED		PTD2/ LLWU_P13	SPI0_SOUT		FTM3_CH2	FTM0_CH2	FLEXPWMA_ A1	I2C0_SCL
96	60	44	PTD3	DISABLED		PTD3	SPI0_SIN		FTM3_CH3	FTM0_CH3	FLEXPWMA_ B1	I2C0_SDA
97	61	45	PTD4/ LLWU_P14	DISABLED		PTD4/ LLWU_P14	SPI0_PCS1	UART0_ RTS_b	FTM0_CH4	FLEXPWMA_ A2	EWM_IN	SPI0_PCS0
98	62	46	PTD5	ADCA_CH6g	ADCA_CH6g	PTD5	SPI0_PCS2	UART0_ CTS_b/ UART0_ COL_b	FTM0_CH5	FLEXPWMA_ B2	EWM_OUT_b	SPI0_SCK
99	63	47	PTD6/ LLWU_P15	ADCA_CH7g	ADCA_CH7g	PTD6/ LLWU_P15	SPI0_PCS3	UART0_RX	FTM0_CH6	FTM1_CH0	FTM0_FLT0	SPI0_SOUT
100	64	48	PTD7	DISABLED		PTD7		UART0_TX	FTM0_CH7	FTM1_CH1	FTM0_FLT1	SPI0_SIN

5.2 Pinout diagrams

The following diagrams show pinouts for the packages. For each pin, the diagrams show the default function. However, many signals may be multiplexed onto a single pin.

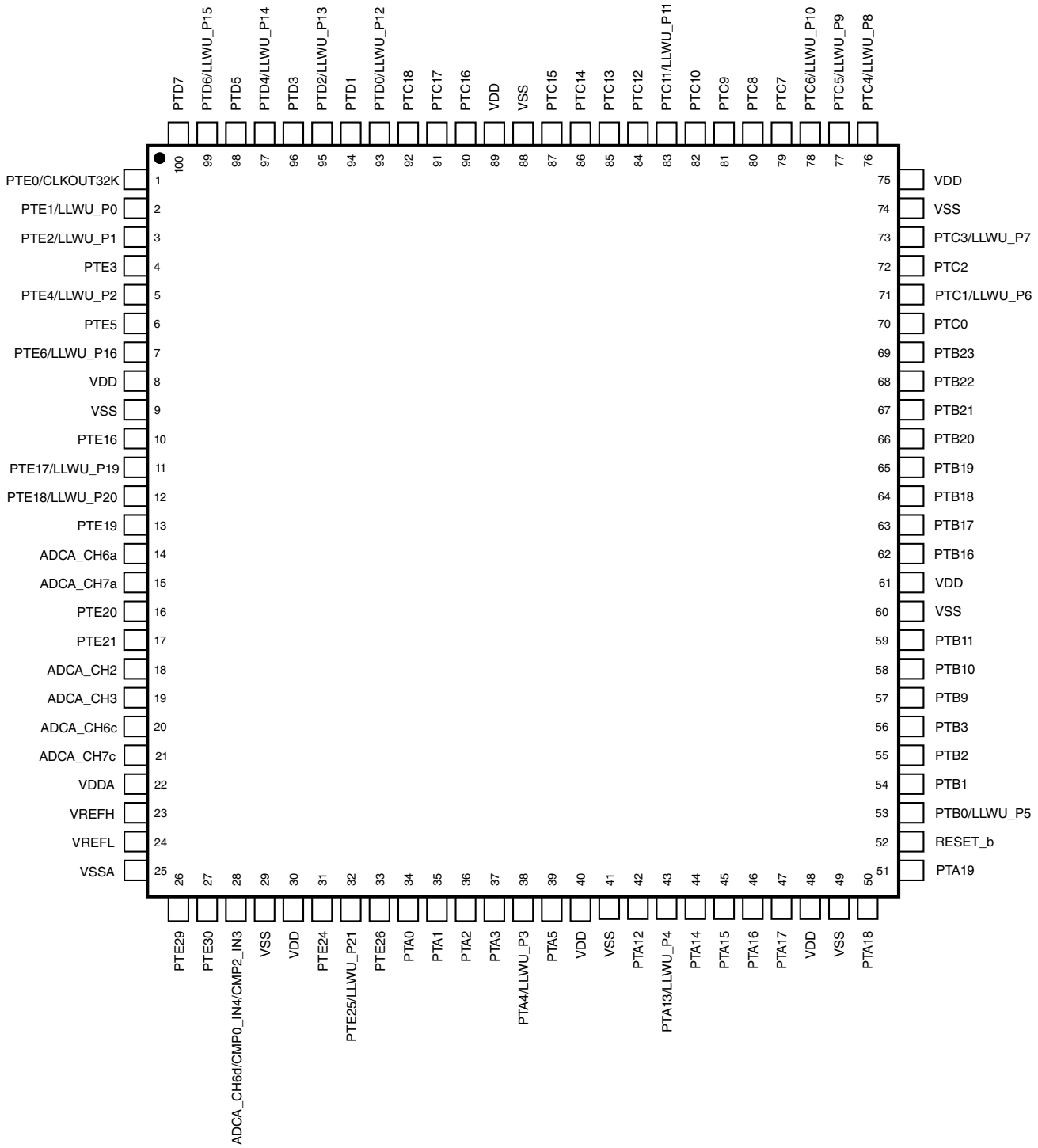


Figure 22. 100-pin LQFP

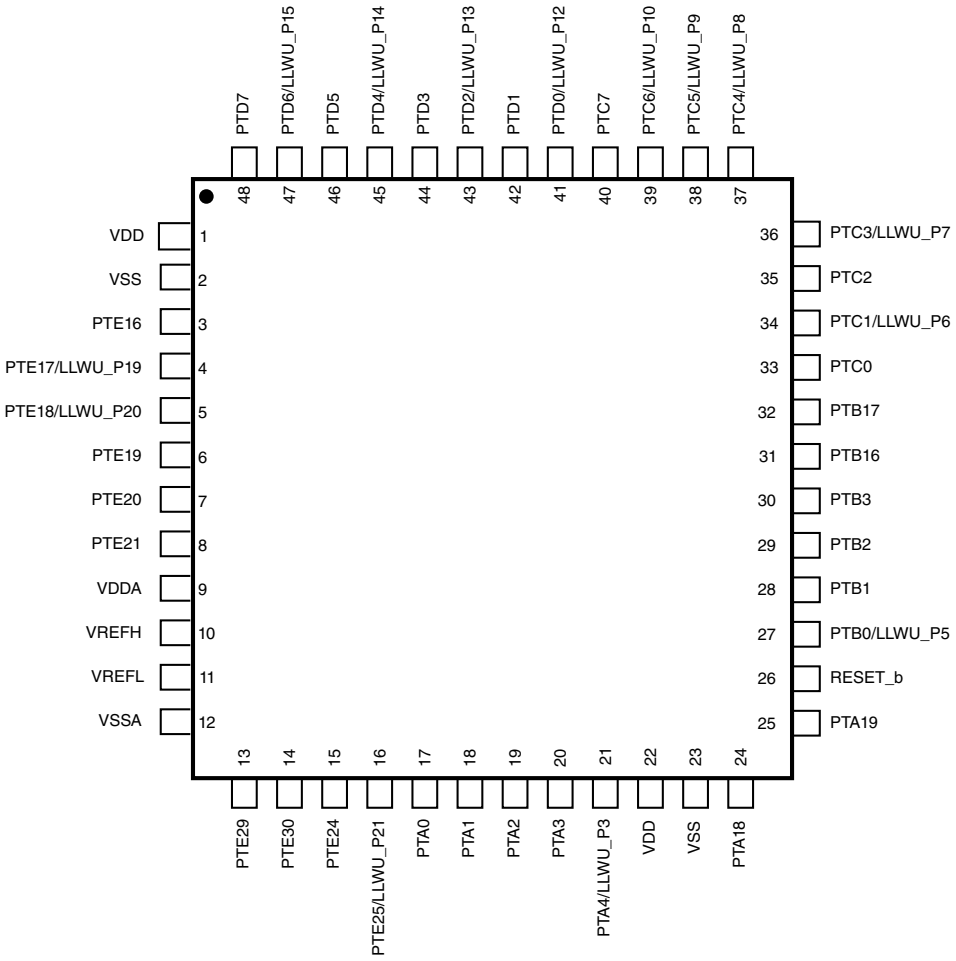


Figure 24. 48-pin LQFP

6 Ordering parts

Field	Description	Values
S	Software type	• P = KMS-PMSM and BLDC • (Blank) = Not software enabled
N	Packaging type	• R = Tape and reel • (Blank) = Trays

7.4 Example

This is an example part number:

MKV46F256VLL16

8 Terminology and guidelines

8.1 Definition: Operating requirement

An *operating requirement* is a specified value or range of values for a technical characteristic that you must guarantee during operation to avoid incorrect operation and possibly decreasing the useful life of the chip.

8.1.1 Example

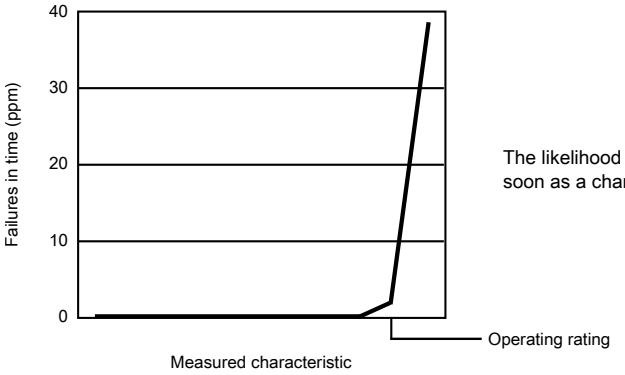
This is an example of an operating requirement:

Symbol	Description	Min.	Max.	Unit
V_{DD}	1.0 V core supply voltage	0.9	1.1	V

8.2 Definition: Operating behavior

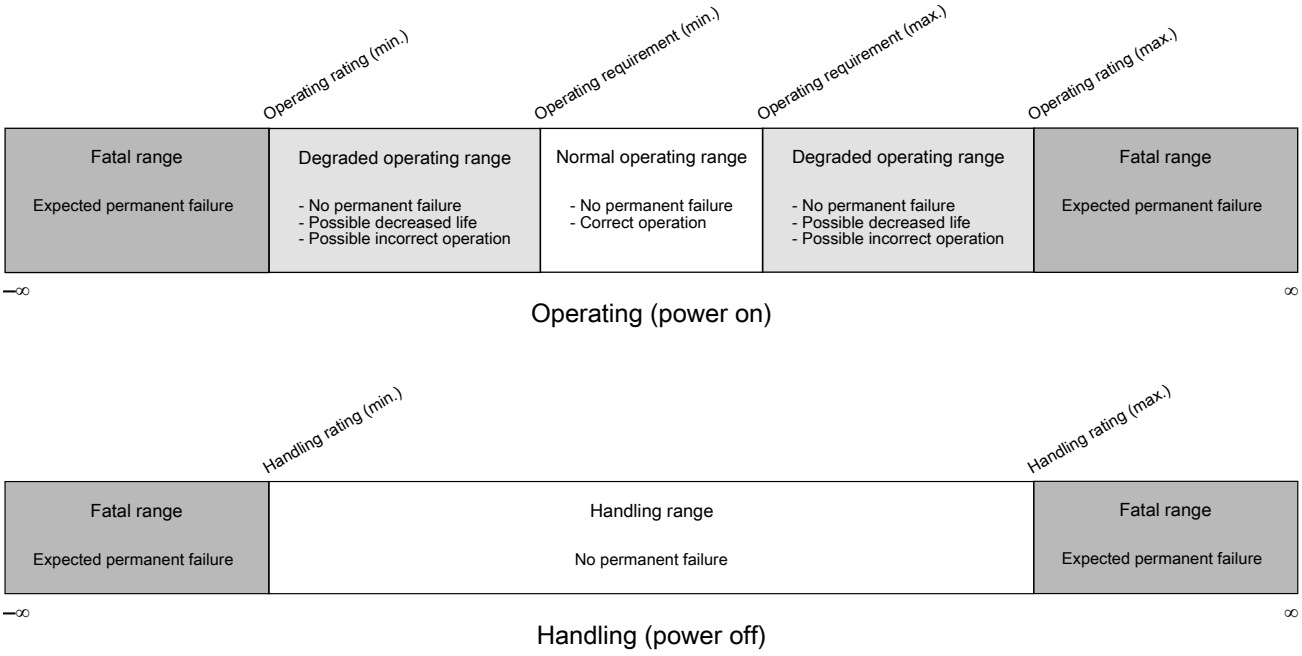
Unless otherwise specified, an *operating behavior* is a specified value or range of values for a technical characteristic that are guaranteed during operation if you meet the operating requirements and any other specified conditions.

8.5 Result of exceeding a rating



The likelihood of permanent chip failure increases rapidly as soon as a characteristic begins to exceed one of its operating ratings.

8.6 Relationship between ratings and operating requirements



8.7 Guidelines for ratings and operating requirements

Follow these guidelines for ratings and operating requirements:

- Never exceed any of the chip's ratings.